

26. (New) The microelectronic device according to claim 25, further including:
an opening in the flexible circuit board;
a bond pad on the microelectronic die; and
a bond ribbon that extends from the bond pad, through the opening, to the second side.
27. (New) The microelectronic device according to claim 25, further including:
an opening in the flexible circuit board;
a bond pad on the microelectronic die;
a bond ribbon that extends from the bond pad, through the opening, to the second side; and
a contact structure attached on the second side.
28. (New) The microelectronic device according to claim 25, further including:
an opening in the flexible circuit board;
a bond pad on the microelectronic die;
a bond ribbon that extends from the bond pad, through the opening, to the second side; and
a solder ball contact structure attached on the second side.
29. (New) The microelectronic device according to claim 25, wherein the fiber reinforced encapsulation material includes a fiber selected from glass, carbon, Kevlar®, ceramic, and metal.
30. (New) The microelectronic device according to claim 25, wherein the fiber reinforced encapsulation material includes a fiber selected from glass, carbon, Kevlar®, ceramic, and metal, and wherein the fiber has a length between 5 and 40 micrometers and a diameter